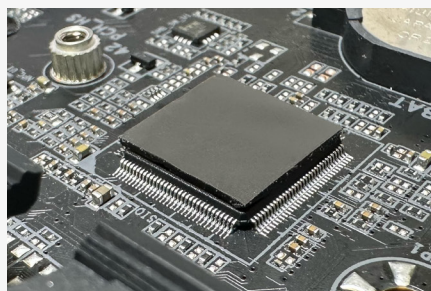


Thermal Pad BDA-8060



Features

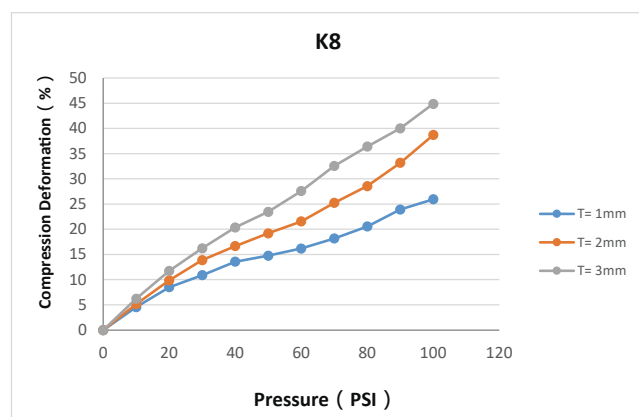
- Thermal Conductivity :8.0W/m-K
- Excellent flame retardancy
- Good Compressibility and Elasticity
- Good electrical insulation performance
- Easy For Installation

Applications

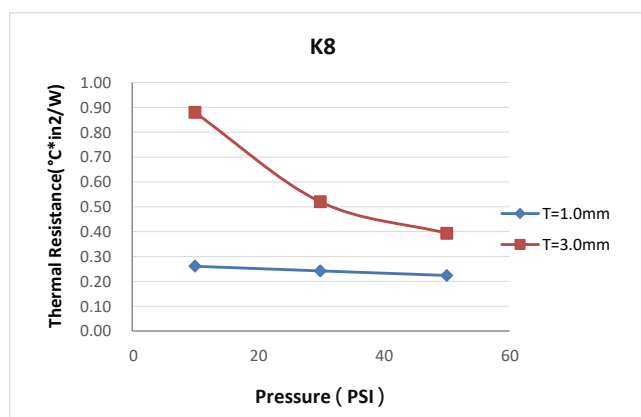
- Communication hardware
- Memory Modules
- Mass Storage Devices
- Automotive Electronics
- Smartphones
- Semiconductor heat sink

BDA -8060 The utility model belongs to a high-performance silicone thermal conductive silicone sheet, which is made of silica gel as a matrix and filled with various high-performance ceramic powders. The utility model has the advantages of low hardness, high thermal conductivity, low thermal resistance, good adhesion on the heat dissipation parts, low insulation and compression stress, etc.

■ Compression Ratio



■ Thermal Resistance VS Pressure



Parameter

Project	Thermal Pad BDA-01 265	Test Method
Thermal Conductivity(W/m-K)	8.0	ASTM D5470
Operating Temperature (°C)	-40~150	—
Color	TBA	Visual
Density (g/cm ³)	3.4	ASTM D792
Thickness Range (mm)	1.0~5.0	ASTM D374
Thickness Tolerance> 1mm	±10%mm	—
Hardness (Shore 00)	50~70	ASTM D2240
Breakdown Voltage (KV AC/mm)	>6.0	ASTM D149
Volume Resistivity (Ohm-cm)	10 ¹³	ASTM D257
Dielectric Constant@1MHz	>6	ASTM D150
UL Flammability Rating	V0	UL 94
ROHS/HF/REACH	PASS	—

Storage in shade, Storage temperature: ≤30 °C, Storage humidity: ≤70%
12 months from the date of manufacture